

VIGON® US

Water-based cleaning medium for flux removal



VIGON® US (US = ultrasonic), based on the MPC® Technology (Micro Phase Cleaning), is a water-based product specifically developed for use in ultrasonic, spray-under-immersion and centrifugal cleaning equipment. It removes all types of flux residues from electronic assemblies, ceramic hybrids, power modules and lead frames.

Areas of application: PCB's, ceramic hybrids, power modules, lead frames		Additional product information:
Low solid flux residues*	++	Application Recommendation: Specific parameters for your cleaning process Technical Information 2: Overview of all fluxes and solder pastes tested Technical Information 3: Material compatibility overview MPC® Technology Sheet: Additional information on MPC® Technology
Rosin-based flux residues*	++	
Water soluble flux residues*	++	
Solder pastes (unsoldered)	++	
SMT or conductive adhesives	★	
Misprinted thick film pastes	+	

++ highly recommended, best results + recommended 0 possible

★ We recommend VIGON® SC 200 or VIGON® SC 202 for this application.

* Valid for all standard, lead-free and lead-based solders

Technical Centers - ① America ② Europe ③ Malaysia ④ East China ⑤ South China Cleaning Process Solutions under Production Floor Conditions



Contact ZESTRON's Process Engineering Team for free-of-charge cleaning trials:

Phone: +1 (703) 393-9880; Email: infoUSA@zestron.com

Advantages compared to other surfactant cleaners:

- Water-based cleaner without flash point or requirements for explosion proof protection.
- The cleaning medium was specifically designed for use in dip tank systems.
- Due to its formulation, VIGON® US can be easily rinsed without leaving residues on the surface.
- Its high bath loading capacity ensures an extended bath life, low maintenance costs and reduced cleaning agent costs.
- VIGON® US works exceptionally well for the cleaning of capillary spaces and is also suitable for cleaning under low standoff components.
- Low odor.
- Halogen free.

Please refer to the material compatibility datasheet (Technical Information 3) prior to cleaning plastics.

TECHNICAL INFORMATION

ZESTRON

North Asia
Shanghai/Shenzhen-China
infochina@zestron.com

South Asia
Kulim-Malaysia
infoasia@zestron.com

America
Manassas, VA-USA
infousa@zestron.com

Europe
Ingolstadt-Germany
info@zestron.com



Process	1.Cleaning	2.Rinsing	3.Drying
Ultrasonic	VIGON® US	DI-water	Hot or circulated air
Spray-under-immersion	VIGON® US	DI-water	Hot or circulated air
Centrifugal cleaning	VIGON® US	DI-water	Hot air

Technical Data: VIGON® US at 20 % concentration.		
Density	(g/ccm) at 20°C/68°F	0.99
Surface tension	(mN/m) at 25°C/77°F	30.8
Boiling range	°C/°F	165 - 212 / 329 - 414
Flash point	°C/°F	None
pH-value	10g/l H ₂ O	11
Vapor pressure	(mbar) at 20°C/68°F	19
Cleaning temperature	°C/°F	40 - 60 / 104 - 140
Solubility in water		Soluble
Application concentration	%	15 - 20
HMIS rating	Health-Flammability-Reactivity	0 - 0 - 0

PRODUCT FEATURES



Extensively tested and suitable for cleaning of LF solder pastes



MPC® Technology ensures an extremely long bath life when processed closed loop



100% compliance with EU guidelines



Product is free of any critical substances according to SIN & SVHC lists

Environmental and health and safety regulations:

- VIGON® US does not contain any halogenated compounds and is environmentally friendly.
- VIGON® US is a non-hazardous material.

Availability:

- VIGON® US is available as a concentrate solution in 1L, 5L or 25L containers and 200L drums.

Storage:

- Store VIGON® US in the original container at a temperature between 5-30°C / 41-86°F.
- The product has a minimum shelf life of 5 years in factory sealed containers.

Alternative product recommendation:

- For application in spray-in-air systems such as inline and batch equipment, we recommend the MPC® based wide-range cleaners VIGON® A 250 and VIGON® A 201.